CH03-HB - Micro SIM Card Connector Hinged Type, 6 Pin, SMT, 1.75mm Profile

1. **General Characteristics**
   - Dimensions: 16.35L x 14.70W x 3.50H mm
   - Weight: Approx. 0.47g
   - Contact principle: Friction Technology
   - Operating position: Shift up / down / horizontal mounting: SMT type (without post)
   - Durability: 5,000 cycles min.

2. **Mechanical Characteristics**
   - Insulation material: LCP UL 94V-0 black
   - Contact terminal phosphor bronze gold plating
   - Metal shell: Stainless steel nickel plating
   - RoHS Directive 2002/95/EC Compliant

3. **Electrical Characteristics**
   - Number of contacts: 6 pins
   - Contact resistance: 100mΩ max
   - Insulation resistance: 1,000,000Ω min
   - Dielectric withstand voltage: 500 V AC

4. **Solderability**
   - IF REWORK: 250°C, 15 sec. max
   - Manual Soldering: 340°C, 3 sec. max

5. **Environmental Characteristics**
   - Operating temperature: -40°C ~ +85°C
   - Operating humidity: 10% ~ 95% RH
   - Storage temperature: -40°C ~ +85°C
   - Storage humidity: 10% ~ 95% RH

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Recommended PCB Layout:
- Use a high-temperature soldering paste.
- Soldering time: 3 seconds, max.

**How to Order**

<table>
<thead>
<tr>
<th>CH03-HB060</th>
<th>0 BR</th>
</tr>
</thead>
<tbody>
<tr>
<td>NO. OF CONTACTS:</td>
<td>6</td>
</tr>
<tr>
<td>PACKAGING TYPE:</td>
<td>R = TAPE &amp; REEL (1000pcs/REEL)</td>
</tr>
</tbody>
</table>

**Scale**: 1:1

**Legend**:
- C1: UV
- C2: P1
- X: P2
- Y: P3

**Type**: CH03-HB

**RoHS Compliant**

**Designated Supplier**: GradConn

**Website**: www.gradconn.com

**Drawing Number**: CH03-HB

**Sheet**: 1 of 3

**Date**: 19 Jun '19

**Revision**: 1.0

**Unit**: mm

**Drawing**: E and 0 E
1. Slide metal lid from 'LOCK' position to 'OPEN' position.

2. Open metal lid to allow Micro SIM card to be inserted.

3. Place Micro SIM card against contacts, chip face down.

4. Close metal lid and slide back to 'LOCK' position.